

Features

- High Output Power: P5dB=50.0dBm (Typ.)
- High Linear Gain: GL=12.0dB (Typ.)
- High Power Added Efficiency: PAE=42% (Typ.)
- Broad Band: 7.7 to 8.5GHz
- Impedance Matched Zin/Zout = 50ohm
- Hermetically Sealed Package

Description

The SGK7785-100A is a high power GaN-HEMT that is internally matched for standard communication bands to provide optimum power and gain in a 500hm system.



ABSOLUTE MAXIMUM RATING (Case Temperature T_c=25 deg.C)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	26	V
Gate-Source Voltage	V _{GS}	-10	V
Total Power Dissipation	P _T	300	W
Storage Temperature	T _{stg}	-55 to +125	deg.C
Channel Temperature	T _{ch}	+250	deg.C

RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
Drain-Source Voltage	V _{DS}		<=24	V
Forward Gate Current	I _{GF}	Rg=25ohm	<=24.4	mA
Reverse Gate Current	I _{GR}	Rg=25ohm	>=-12.8	mA
Channel Temperature	T _{ch}		<+192	deg.C

ELECTRICAL CHARACTERISTICS (Case Temperature T_c=25 deg.C)

Item	Symphol	Condition	Limit			Unit	
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	
Saturated Drain Current	I _{DSS}	$V_{DS}=10V$, $V_{GS}=0V$	-	26.0	-	А	
Trans Conductance	Gm	V _{DS} =24V, I _{DS} =5.3A	-	12.0	-	S	
Pinch-off Voltage	VP	V_{DS} =24V, I_{DS} =5.3mA	-	-3.0	-	V	
Output Power at 5dB G.C.P.	P _{5dB}		49.0	50.0	-	dBm	
Linear Gain at Pin=28.0dBm	GL	$V_{DS}=24V(typ.)$	11.0	12.0	-	dB	
Drain Current at 5dB G.C.P.	I _{DSR}	I _{DS(DC)} =4.0A(typ.) f=7.7 to 8.5 GHz	-	10.0	14.0	A	
Power Added Efficiency at 3dB G.C.P.	PAE		-	42.0	-	%	
Gain Flatness	ΔG	Vgs-constant	-	-	1.2	dB	
3rd Order Inter Modulation Distortion	IM3	f=7.7GHz, 8.5GHz $\Delta f=10MHz$, 2-tone Test Pout=44.0dBm (S.C.L.)	-25.0	-	-	dBc	
Thermal Resistance	R _{th}	Channel to Case	-	0.55	0.75	deg.C/W	
Channel Temperature Rise	ΔT_{ch}	$(V_{DS} \times I_{DSR} - Pout + Pin) \times R_{th}$	-	88	140	deg.C	
		G.C.P. : Gain Compre	ession Poir	nt, S.C.L.	: Single (Carrier Level	

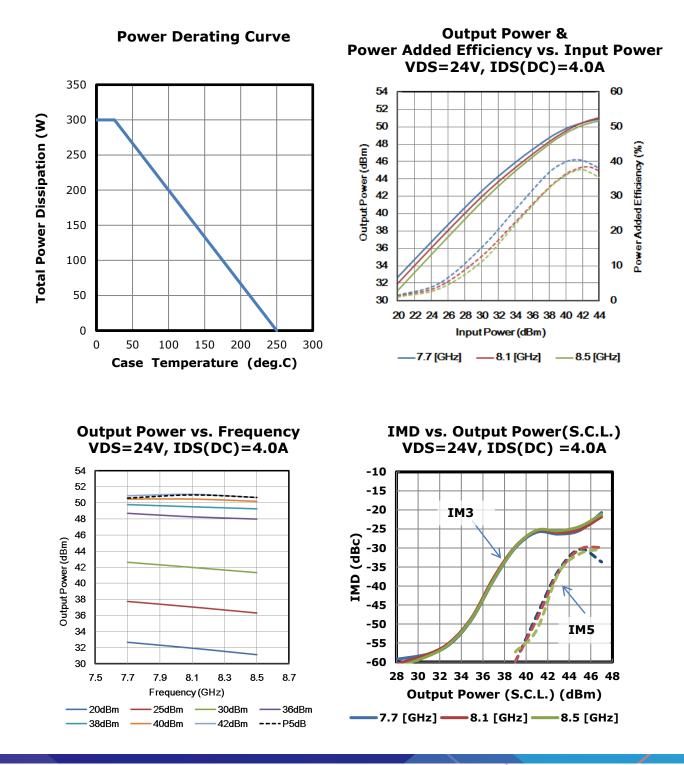
CASE STYLE	I2F	
RoHS Compliance	YES	
ESD	Class 1C	1000V to < 2000V

Note : Based on ANSI/ESDA/JEDEC JS-001-2012(C=100pF, R=1.5kohm)



SGK7785-100A C-Band Internally Matched GaN-HEMT

• **RF Characteristics**



Edition 1.2 Jun. 2020



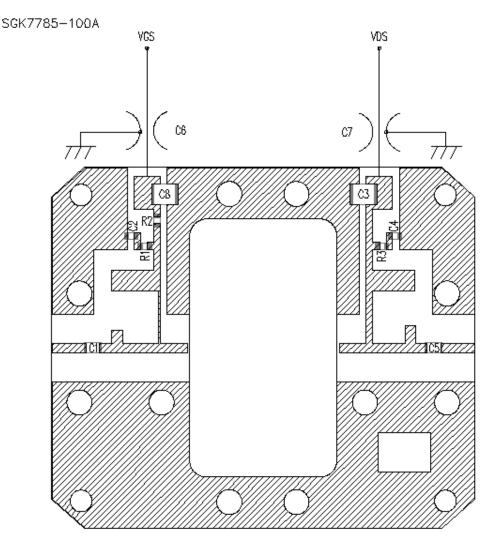
• S-Parameter

Freq.	S11	S11 S21			S12		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
7500 MHz	0.731	17.2	2.878	160.4	0.057	96.6	0.302	16.0
7600 MHz	0.706	5.7	2.969	145.0	0.060	80.8	0.297	-1.7
7700 MHz	0.681	-2.2	3.035	133.3	0.063	69.1	0.291	-13.7
7800 MHz	0.650	-9.9	3.130	121.9	0.065	56.6	0.282	-26.3
7900 MHz	0.600	-19.9	3.281	105.8	0.069	40.1	0.252	-42.0
8000 MHz	0.551	-26.8	3.457	93.8	0.073	27.0	0.219	-55.8
8100 MHz	0.485	-34.0	3.622	80.0	0.076	14.3	0.169	-76.3
8200 MHz	0.366	-44.3	3.904	59.9	0.084	-4.6	0.099	-144.1
8300 MHz	0.240	-45.3	4.014	42.9	0.088	-21.3	0.139	150.1
8400 MHz	0.144	-15.3	3.961	25.3	0.089	-38.5	0.244	115.4
8500 MHz	0.218	25.0	3.711	3.0	0.087	-59.7	0.391	86.8
8600 MHz	0.321	28.3	3.491	-11.8	0.084	-75.0	0.475	68.6
8700 MHz	0.406	22.9	3.225	-26.2	0.080	-88.7	0.538	54.8



SGK7785-100A C-Band Internally Matched GaN-HEMT

• Amplifier Circuit Outline



C1	2.0pF
C2	1000pF
C3	0.1uF
C4	1000pF
C5	2.0pF
Cδ	1000pF
C7	1000pF
C8	0.1uF
R1	51 0
R2	25 <u>0</u>
R3	519

Rogers R04003C

h=0.542mm €r=3.38

Cu=18um Unit:mm

C1 , C5 : ATC 600F(0805) , +/- 0.1pF

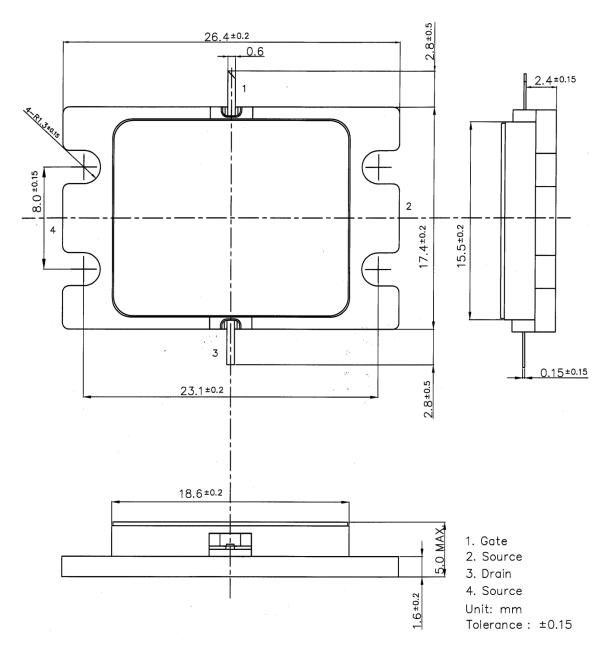
C6, C7: EMI FILTER MARUWA (FTA352AR102S-S)



SGK7785-100A C-Band Internally Matched GaN-HEMT

• Package Out Line

Case Style: I2F





For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product. This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

Any information, such as descriptions of a function and examples of application circuits, in this document are presented solely as a reference for the purpose to show examples of operations and uses of Sumitomo Electric semiconductor device(s); Sumitomo Electric does not warrant the proper operation of the device(s) with respect to its use based on such information. When the user develops equipment incorporating the device(s) based on such information, they must assume full responsibility arising out of using such information. Sumitomo Electric assumes no liability for any damages whatsoever arising out of the use of the information.

Any information in this document, including descriptions of function and schematic diagrams, shall not be construed as a license for the use or exercise of any intellectual property right, such as patent right or copyright, or any other right of Sumitomo Electric or any third party nor does Sumitomo Electric warrant non-infringement of any third-party's intellectual property right or other right by using such information. Sumitomo Electric assumes no liability for any infringement of the intellectual property rights or other rights of third parties which would result from the use of information contained herein.

The products described in this document are designed, developed and manufactured as contemplated for general use, including, without limitation, ordinary industrial use, general office use, personal use, and household use, but are not designed, developed and manufactured as contemplated (1) for use accompanying fatal risks or dangers that, unless extremely high safety is secured, could have a serious effect to the public, and could lead directly to death, personal injury, severe physical damage or other loss (i.e., nuclear reaction control in nuclear facility, aircraft flight control, air traffic control, mass transport control, medical life support system, missile launch control in weapon system), or (2) for use requiring extremely high reliability (i.e., submersible repeater and artificial satellite). Please note that Sumitomo Electric will not be liable to the user and/or any third party for any claims or damages arising from the aforementioned uses of the products.

Any semiconductor devices have an inherent chance of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of excessive current levels and other abnormal operating conditions.

If any products described in this document represent goods or technologies subject to certain restrictions on export under the Foreign Exchange and Foreign Trade Law of Japan, the prior authorization of the Japanese government will be required for export of those products from Japan.

http://www.sedi.co.jp/

ATTENTION

Information in this document is subject to change without notice.